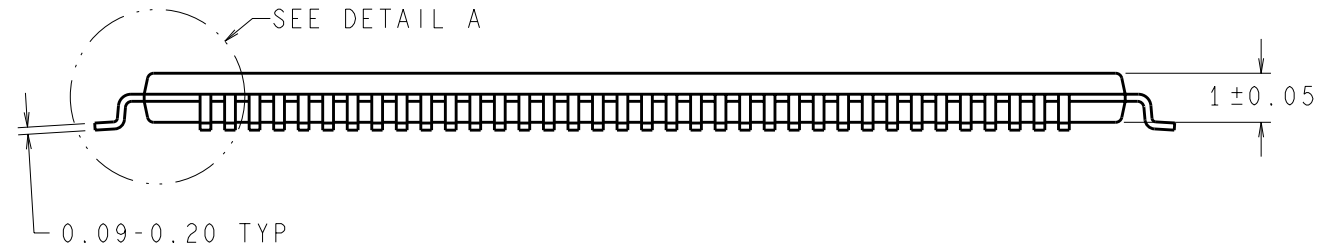


0.5 TYP
 0.22±0.05 TYP
 ⌀ 0.08 M C A S B S

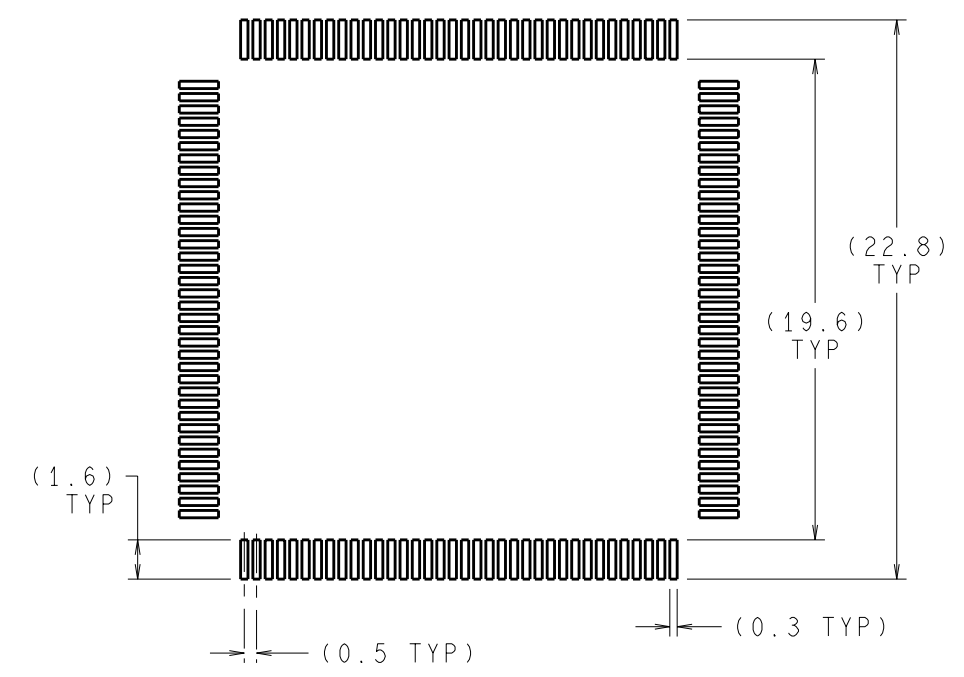


DIMENSIONS ARE IN MILLIMETERS

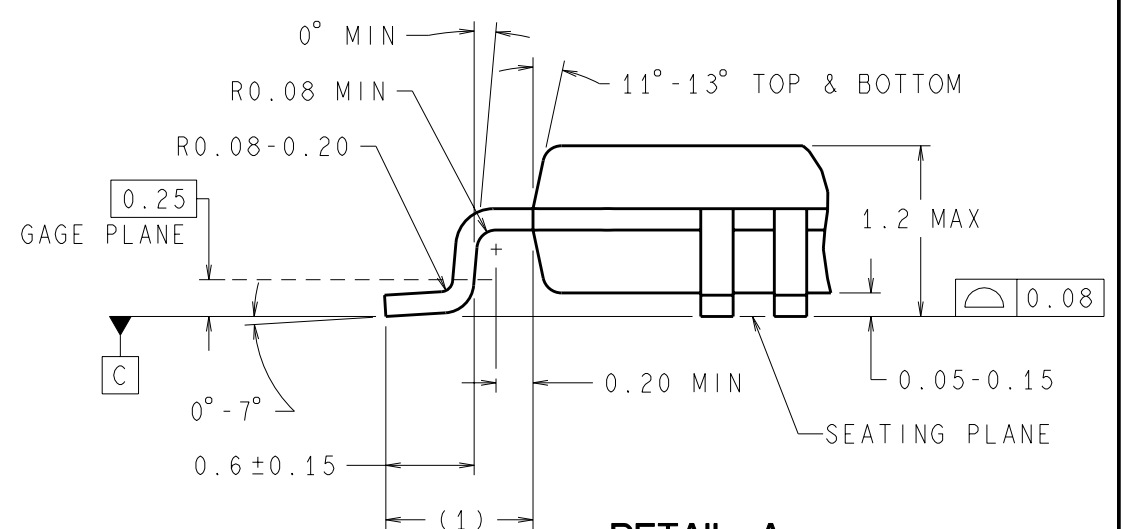
NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:
7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)
THICKNESS ON COPPER.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
- REFERENCE JEDEC REGISTRATION MS-026, VARIATION AFB, DATED FEBRUARY 1999.

REVISIONS			
LTR	DESCRIPTION	E.C.N.	DATE
A	RELEASE TO DOCUMENT CONTROL	109	05/08/2000



LAND PATTERN RECOMENDATION



DETAIL A
TYP, SCALE: 30X

APPROVALS	DATE	National Semiconductor			
DRAWN MARTA SUCHY	05/08/2000	2900 Semiconductor Dr., Santa Clara, CA 95052-8090			
DFTG. CHK. THANH LEQUANG	05/08/2000	TQFP, JEDEC METRIC, 20 X 20 X 1.0mm, 144 LEAD, 0.5mm PITCH			
ENGR. CHK. RANDALL WALBERG	05/08/2000				
		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	(SC)MKT-VNA144A	A
DO NOT SCALE DRAWING				SHEET 1 of 1	